

Wafer-level testing of the readout chip of the CMS Inner Tracker for HL-LHC

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Introduction

- CMS Inner Tracker for High-Luminosity LHC (HL-LHC): pixel detector instrumented with 10⁴ CMS **Readout Chips (CROCs)**
- CROC characteristics:
 - 65 nm technology readout chip
 - Developed by the joint ATLAS-CMS RD53 collaboration
 - 432×336 pixels in approximately 4 cm^2
 - Very complex digital architecture for high energy physics
 - Serial powering: chips powered via current source
 - 20 wafers produced for the prototype chip CROCv1
- Wafer-level testing (WLT) activity
 - Testing CROCs on wafers to **discard chips with** manufacturing problems
 - Critical importance for the detector: 30 % of wafer could be bad!
 - Also important to get calibration data and to characterise the prototype chip



Results

Fabio Luongo^{1,2}

• Average yield of the 8 tested CROCv1 wafers for hybridisation: 73 %



Logos on a CROCv1 chip

Materials and methods

- Waferprobing facility: clean room of the INFN-TO Technological Laboratory
- 8 CROCv1 wafers for hybridisation (138 chips / wafer)
- Completely automated testing procedure
- Chip testing requires about 8 min (18 h for each wafer)

Wafer-level testing hardware

- Probe station: Cascade Microtech CM300xi (semi-automated)
- Probe card: has 198 micrometric tungsten needles to contact the chip pads on the wafer
- Auxiliary card: used for probe card control from PC
- DAQ board: FPGA-based FC7
- Remotely controllable instruments

Wafer-level testing software

- WLT software (Python): **croc_wlt**
- DAQ software (C++): Ph2_ACF

• Chip testing procedures

- Chip powering and measurement of power consumption
- Measurement of chip signals
- Chip trimming (main reference current and core voltages)
- Communication testing
- Registers verification
- Chip calibrations (ADC, DACs, ring oscillators and T sensors)
- Voltage regulator IV
- Chip front-end testing (occupancy and S-curves)

- Preliminary wafer maps for the 8 tested wafers, sorted by wafer identifier
- Rejected chips: 220 out of 1104 (20%) marked red and discarded
 - Most rejections due to **power anomalies** or **failed/marginal chip trimming**





Calibration data

MIN: 0.709 160 MAX: 1.210

AVG: 0.800

3.3%

140 MED: 0.800 RMS: 0.026

120

100

80

60

40

20

0

0.6

0.7

Chips

- Collected calibration data for hundreds of chips
- Chip trimming (reference current and VDDA/D)
- ADC, DAC, ring oscillators, temperature sensors
- Calibration information will be stored in a CMS database
- Data will also be used to produce and test modules

Characterisation data

- Large dataset
- Analog current after chip calibration: $(800 \pm 26) \text{ mA}$
- Digital current after chip calibration: $(669 \pm 11) \text{ mA}$
- (421 ± 19) e threshold dispersion before tuning at 3100 e; after tuning: (35.2 ± 1.7) e
- Much more



Left, center figures: calibrated analog current and VDDA distributions; right figure: threshold dispersion after tuning



Left figure: CM300xi probe station; top right figure: wafer-level *testing hardware; bottom right figure: CROCv1 wafer (*300 mm Ø)

Discussion

- Wafer-level testing setup developed in Torino successfully commissioned for first waferprobing campaign on prototype readout chip for the HL-LHC CMS Inner Tracker
- Waferprobing data used to characterise the prototype chip and to get calibration information
- The tested chips will be used to produce prototype modules

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References

- The Phase-2 Upgrade of the CMS Tracker CMS Collaboration (2017). Link: cds.cern.ch/record/2272264
- Chip reference manuals. Link: cds.cern.ch/record/2665301
- Wafer-level testing software repository. Link: gitlab.cern.ch/croc_testing/croc_wlt

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